

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A semiconductor manufacturing device ~~having~~
~~a processing chamber, the semiconductor manufacturing device comprising:~~

a processing chamber having an opening, the opening being hermetically
sealed by bellows and by a vertically movable pedestal to form an internal space for
processing semiconductor wafers;

a wafer holder, disposed within said space, for holding a semiconductor
wafer, said holder being formed with a plurality of through-holes extending vertically
through a front, wafer-carrying side and an opposing back side of the holder set-up
~~within the processing chamber;~~

a pedestal;

a plurality of lift pins disposed in said processing chamber, with one end of
each of said lift pins being anchored to said processing chamber, and an opposite
end of each of said lift pins being free to move in a corresponding one of said
through-holes;

a plurality of support pieces ~~mounted on~~ retained in said space by said
pedestal;

said lift pins and said support pieces being therein arranged, and said bellows
and said pedestal being configured, such that maximally lowering said

pedestal thrusts said lift pins out of said through-holes along said wafer
carrying face; and
~~a hermetic seal is formed between said pedestal and said chamber.~~

Claims 2-5 (canceled)

Claim 6 (new): The semiconductor manufacturing device of claim 1, wherein
said bellows are disposed outside said processing chamber.